



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Benfer David W	Contact Title	Product Compliance Engineer for DND		
Company Unique ID	TE Connectivity	Response Date	2016-04-12	Contact Email	dave.benfer@te.com				
Contact Phone Number	717-986-3725								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	2041119-1	Amount	1170.7	Version	-	Identity			
Manufacturer Item Name	mSATA/mini PCI-E 4H Type I G/F	Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EUroHS-0508	Product(s) meets EU RoHS requirement without any exemptions								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-0615	REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH								
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Material	1	SOLDER PEGS_Brass				1.0	22.6	mg	
Substance	2	Zinc	Supplier	7440-66-6	35.7546	1.0	8.08054	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0015	1.0	3.39E-4	mg	
Substance	2	Copper	Supplier	7440-50-8	64.23	1.0	14.51598	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0082	1.0	0.0018532	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0057	1.0	0.0012882	mg	
Material	1	Tin Plating for SOLDER PEGS				1.0	0.53	mg	
Substance	2	Tin	Supplier	7440-31-5	99.9001	1.0	0.52947	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0999	1.0	5.2947E-4	mg	
Material	1	Gold Plating for LOW CONTACT				1.0	0.0205	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.0204385	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	1.0	6.15E-5	mg	
Material	1	UP CONTACT_Phosphor Bronze				1.0	171.6	mg	
Substance	2	Zinc	Supplier	7440-66-6	5.0E-4	1.0	8.58E-4	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.085	1.0	0.14586	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0807	1.0	0.13848	mg	
Substance	2	Tin	Supplier	7440-31-5	5.6665	1.0	9.72371	mg	
Substance	2	Copper	Supplier	7440-50-8	94.1562	1.0	161.57204	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0081	1.0	0.0138996	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.005148	mg	
Material	1	Nickel Plating for UP CONTACT				1.0	3.614	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	3.59593	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.4	1.0	0.014456	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.003614	mg	

Material	1	Nickel Plating for LOW CONTACT				1.0	1.976	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	1.96612	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.4	1.0	0.007904	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.001976	mg	
Material	1	HOUSING_LC P E6808L				1.0	884.2557	mg	
Substance	2	Glass, oxide, chemicals	Supplier	65997-17-3	20.0	1.0	176.85114	mg	
Substance	2	Talc (Mg3H2(SiO3)4)	Supplier	14807-96-6	10.0	1.0	88.42557	mg	
Substance	2	Carbon black	Supplier	1333-86-4	1.0	1.0	8.84256	mg	
Substance	2	1,3-Benzenedicarboxylic acid, polymer with 1,4-benzenedicarboxylic acid, [1,1-biphenyl]-4,4-diol and 4-hydroxybenzoic acid	Supplier	60088-52-0	69.0	1.0	610.13643	mg	
Material	1	Nickel Plating for SOLDER PEGS				1.0	0.27	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	0.26865	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	2.7E-4	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.4	1.0	0.00108	mg	
Material	1	Gold Plating for UP CONTACT				1.0	0.0338	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.0336986	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	1.0	1.014E-4	mg	
Material	1	LOW CONTACT_Phosphour Bronze				1.0	85.8	mg	
Substance	2	Copper	Supplier	7440-50-8	94.1562	1.0	80.78602	mg	
Substance	2	Zinc	Supplier	7440-66-6	5.0E-4	1.0	4.29E-4	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.085	1.0	0.07293	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0081	1.0	0.0069498	mg	
Substance	2	Tin	Supplier	7440-31-5	5.6665	1.0	4.86186	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0807	1.0	0.0692406	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.002574	mg	